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High Speed Laser Depaneling Solution

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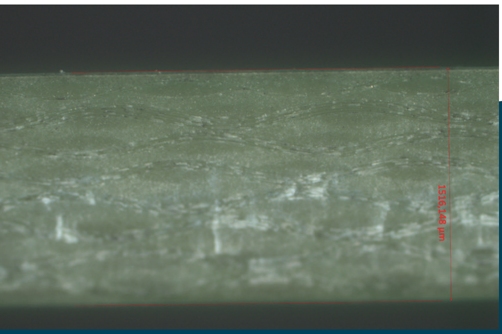
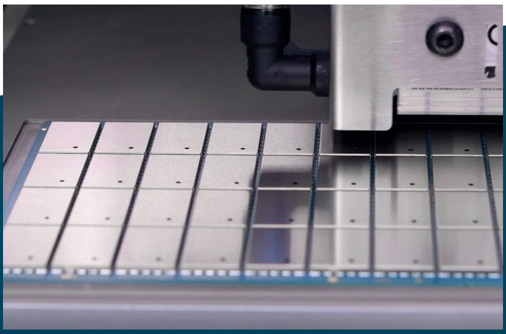
Benefits

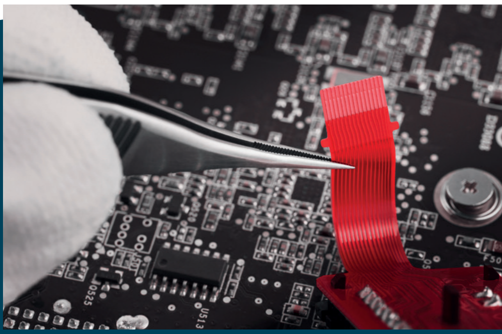
- With FULL CUT process (cut without webs), higher density of panels per printed circuit board
- Free cut for complex contours (e.g. circle shapes)
- Dedicated solution for PCB depaneling
- High edge quality and less residuals
- No carbonization
- Industry 4.0 ready
- Automatic camera calibration
- Automated routines for reference runs
- Automated vision system for precision alignment and scaling, offset, trapezoidal and rotation compensation

Options

- 2nd process head (scanner)
- InnoLas Postprocessor for CAD file transfer
- Exhaust system
- MES Interface
- Auto focus
- Integrated process metrology







Technical Data

Optic	High Speed Scanner
Axis	X-Y / Z
Accuracy	< ± 25 µm (± 0.984 Mils)
Repeatability	< ± 5 µm (± 0.197 Mils)
Substrate Size	18" x 18" (457 x 457 mm)
Material	Rigid and Flex PCB
Image System	InnoLas µVision
Software	Windows 10; IoT

Automation

- Fully and semi-automatic InnoLas Automation
- Customized automation solutions
- Stand Alone System and inline integration
- SMEMA compatible with 3rd party automation

Laser processes

- Laser Depaneling
- Laser Ablation

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